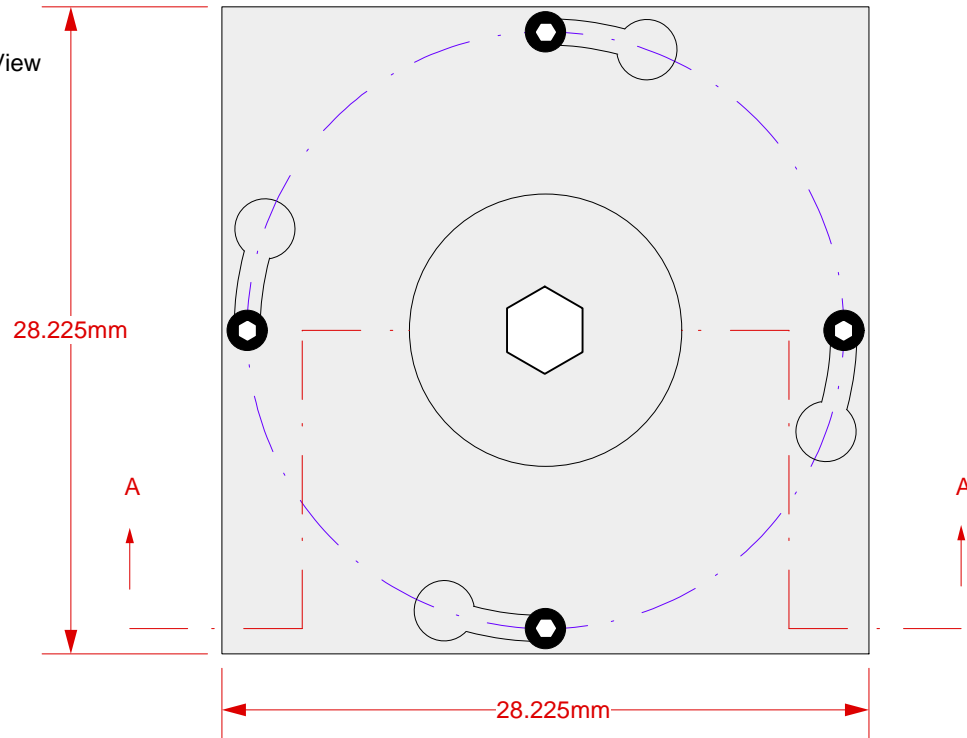


GHz BGA Socket - Direct mount, solderless

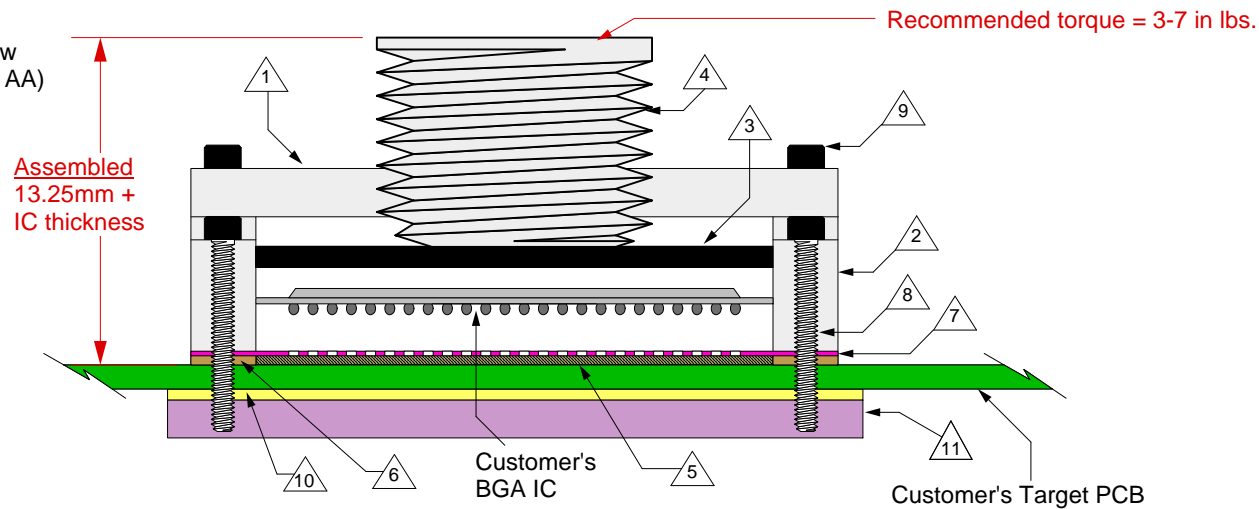
Top View



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)



- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Black anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

SG-BGA-6043 Drawing

© 2009 IRONWOOD ELECTRONICS, INC.
11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: NA

Rev: E

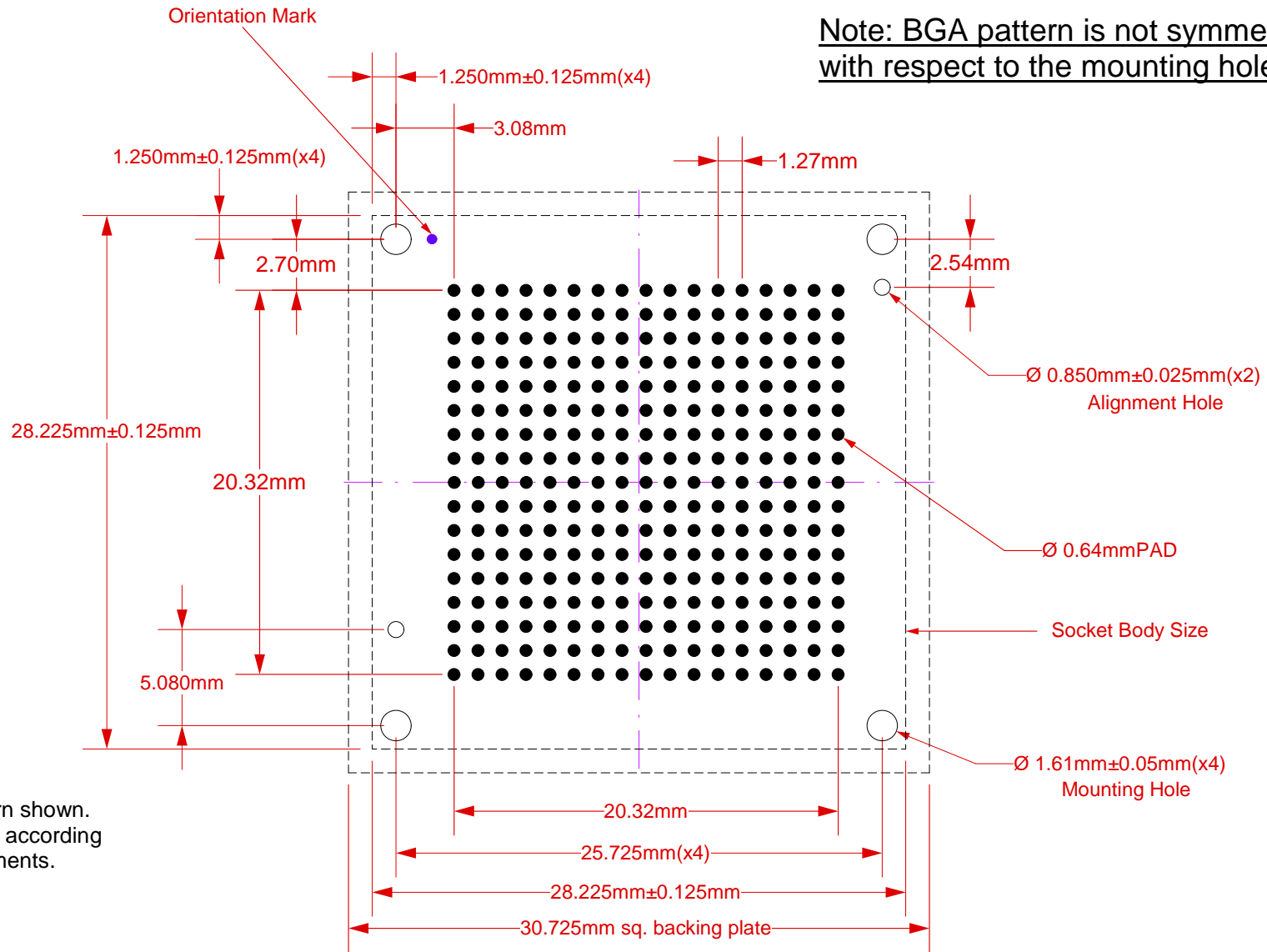
Drawing: H. Hansen

Date: 3/28/02

File: SG-BGA-6043 Dwg.mcd

Modified: 7/6/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.




Note: Full BGA pattern shown.
Please adjust pattern according
to individual requirements.

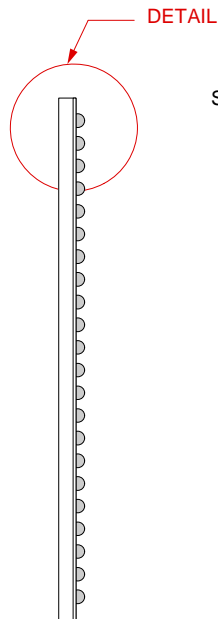
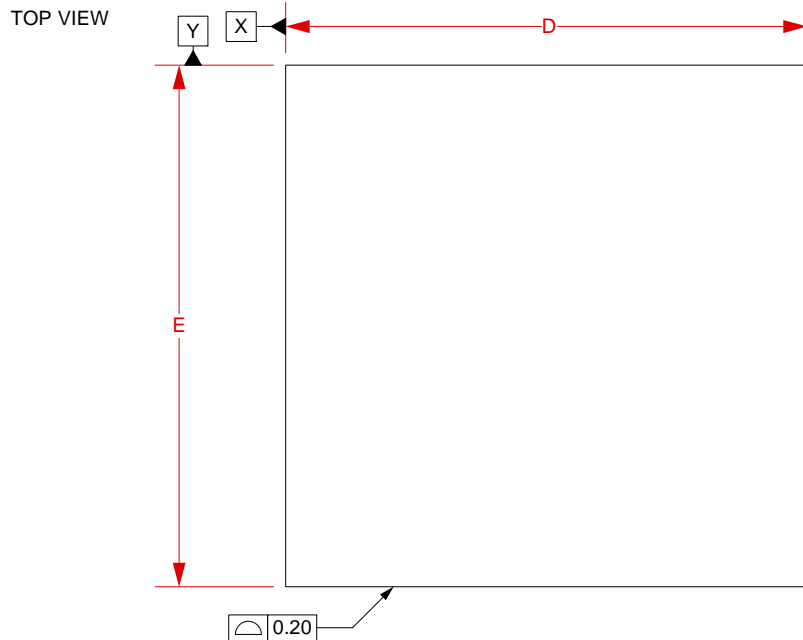
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

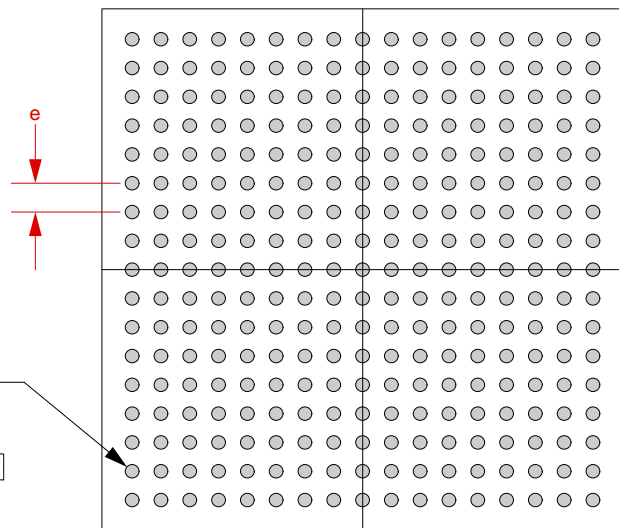
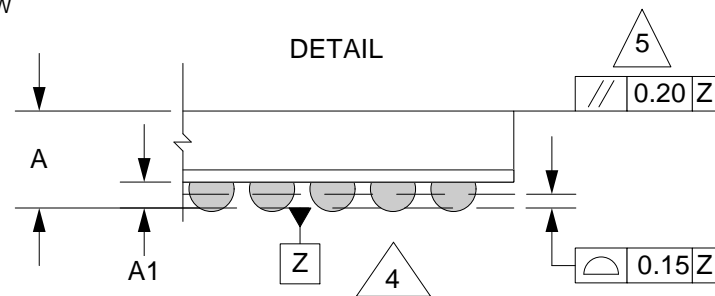
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

	SG-BGA-6043 Drawing	Status: Released	Scale: 3:1	Rev: E
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 3/28/02
		File: SG-BGA-6043 Dwg.mcd	Modified: 7/6/09, AE	



SIDE VIEW



BOTTOM VIEW

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.


3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

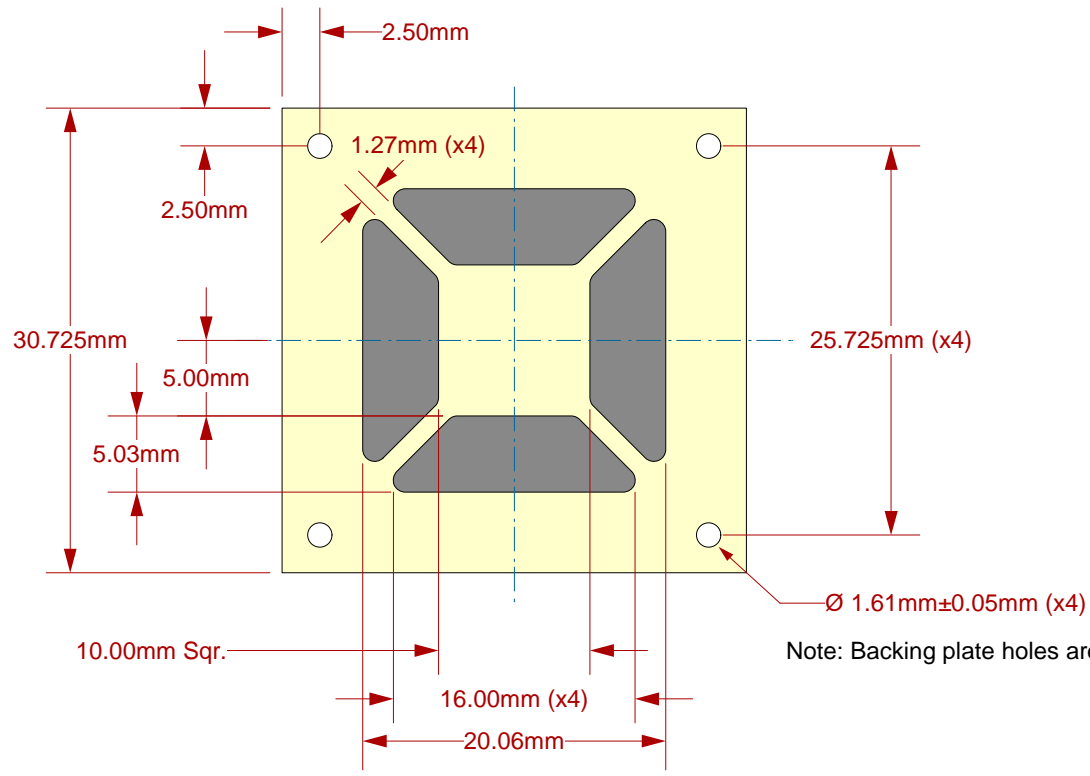
5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.33
A1	0.5	0.7
b		0.9
D	23.00 BSC	
E	23.00 BSC	
e	1.27 BSC	

Array 17x17

	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: -	Rev: E
		Drawing: H. Hansen		Date: 3/28/02
		File: SG-BGA-6043 Dwg.mcd		Modified: 7/6/09, AE

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

	SG-BGA-6043 Drawing	Status: Released	Scale: NA	Rev: E
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 3/28/02
		File: SG-BGA-6043 Dwg.mcd	Modified: 7/6/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.